



Material Content Data Sheet



Sales Product Name	IFX1021SJ			Issued		29. August 2013		
MA#	MA000981512							
Package	PG-DSO-8-3			Weight*		83.14 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.228	2.68	2.68	26794	26794
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		112	
	non noble metal	zinc	7440-66-6	0.037	0.04		446	
	non noble metal	iron	7439-89-6	0.742	0.89		8921	
	non noble metal	copper	7440-50-8	30.114	36.22	37.16	362225	371704
wire	noble metal	gold	7440-57-5	0.215	0.26	0.26	2591	2591
encapsulation	organic material	carbon black	1333-86-4	0.141	0.17		1701	
	plastics	epoxy resin	-	5.515	6.63		66333	
	inorganic material	silicondioxide	60676-86-0	41.478	49.91	56.71	498912	566946
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9789	9789
plating	noble metal	silver	7440-22-4	0.541	0.65	0.65	6512	6512
glue	plastics	epoxy resin	-	0.228	0.27		2741	
	noble metal	silver	7440-22-4	1.074	1.29	1.56	12923	15664
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

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